February 1999

FAIRCHILD SEMICONDUCTOR™

FDG312P

P-Channel 2.5V Specified PowerTrench™ MOSFET

General Description

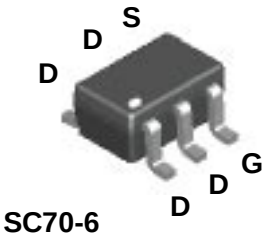
This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance. These devices are well suited for portable electronics applications.

Applications

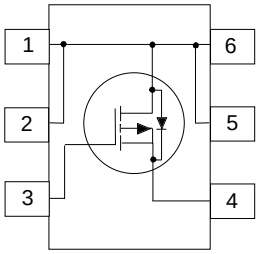
- Load switch
- Battery protection
- Power management

Features

- -1.2 A, -20 V. $R_{DS(on)}$ = 0.18 Ω @ V_{GS} = -4.5 V
  $R_{DS(on)}$ = 0.25 Ω @ V_{GS} = -2.5 V.
- Low gate charge (3.3 nC typical).
- High performance trench technology for extremely low $R_{DS(ON)}$.
- Compact industry standard SC70-6 surface mount package.



SC70-6



Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		-20	V
V_{GSS}	Gate-Source Voltage		± 8	V
I_D	Drain Current - Continuous	(Note 1)	-1.2	A
	- Pulsed		-6	
P_D	Power Dissipation for Single Operation	(Note 1a)	0.75	W
		(Note 1b)	0.55	
		(Note 1c)	0.48	
T_J, T_{stg}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1)	260	°C/W

Package Outlines and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
.12	FDG312P	7''	8mm	3000 units

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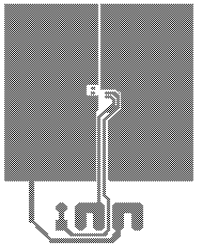
DMOS Electrical Characteristics

T_A = 25°C unless otherwise noted

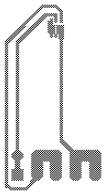
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = -250 μA	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		-19		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -16 V, V_{GS} = 0 V			-1	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 8 V, V_{DS} = 0 V			100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -8 V, V_{DS} = 0 V			-100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = -250 μA	-0.4	-0.9	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		2.5		mV/°C
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = -4.5 V, I_D = -1.2 A V_{GS} = -4.5 V, I_D = -1.2 A @125°C V_{GS} = -2.5 V, I_D = -1 A		0.135 0.200 0.187	0.18 0.29 0.25	Ω
$I_{D(on)}$	On-State Drain Current	V_{GS} = -4.5 V, V_{DS} = -5 V	-3			A
g_{FS}	Forward Transconductance	V_{DS} = -5 V, I_D = -1.2 A		3.8		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = -10 V, V_{GS} = 0 V, f = 1.0 MHz		330		pF
C_{oss}	Output Capacitance			80		pF
C_{rss}	Reverse Transfer Capacitance			35		pF
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = -5 V, I_D = -0.5 A, V_{GS} = -4.5 V, R_{GEN} = 6 Ω		7	15	ns
t_r	Turn-On Rise Time			12	22	ns
$t_{d(off)}$	Turn-Off Delay Time			16	26	ns
t_f	Turn-Off Fall Time			5	12	ns
Q_g	Total Gate Charge	V_{DS} = -10 V, I_D = -1.2 A, V_{GS} = -4.5 V		3.3	5	nC
Q_{gs}	Gate-Source Charge			0.8		nC
Q_{gd}	Gate-Drain Charge			0.7		nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current				-0.6	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = -0.6 A (Note 2)		-0.83	-1.2	V

Notes:

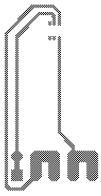
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) 170°C/W when mounted on a 1 in^2 pad of 2oz copper.



b) 225°C/W when mounted on a half of package sized 2oz. copper.



c) 260°C/W when mounted on a minimum pad of 2oz copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

Typical Characteristics

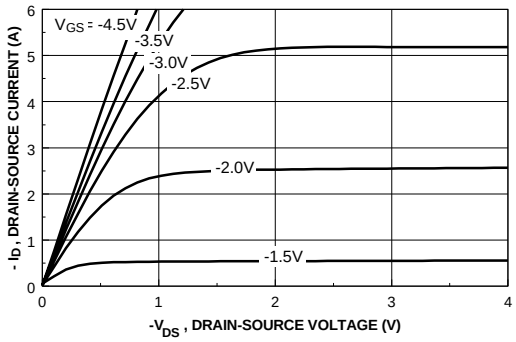


Figure 1. On-Region Characteristics.

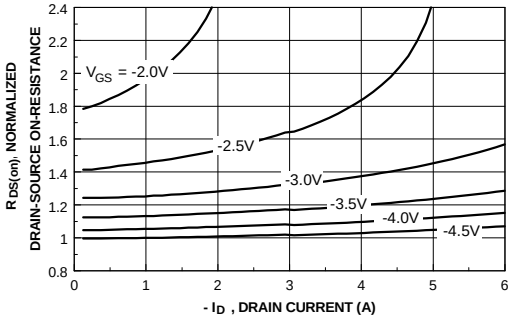


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

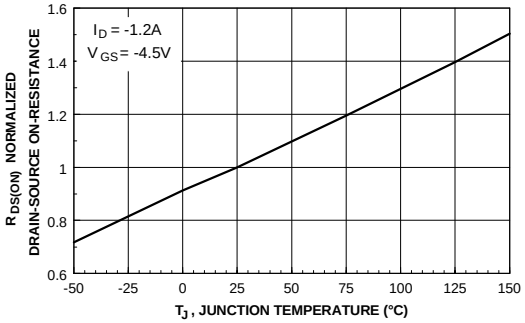


Figure 3. On-Resistance Variation with Temperature.

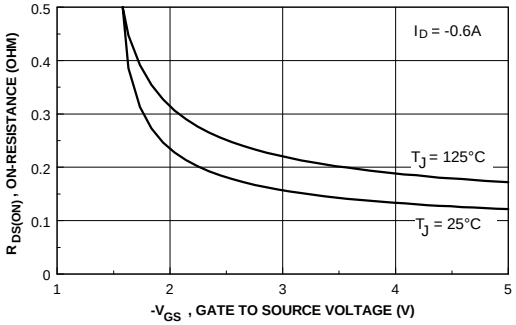


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

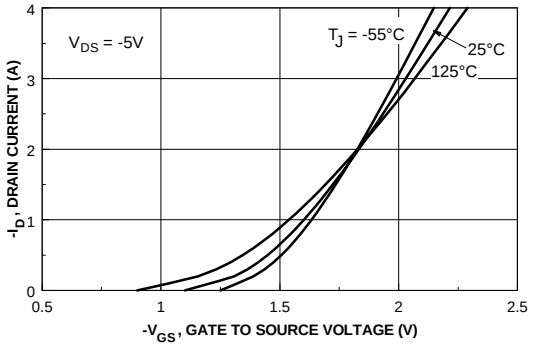


Figure 5. Transfer Characteristics.

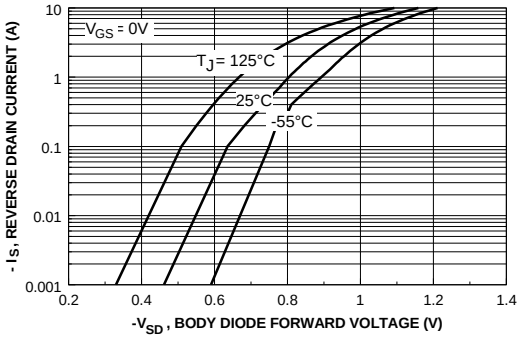


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)

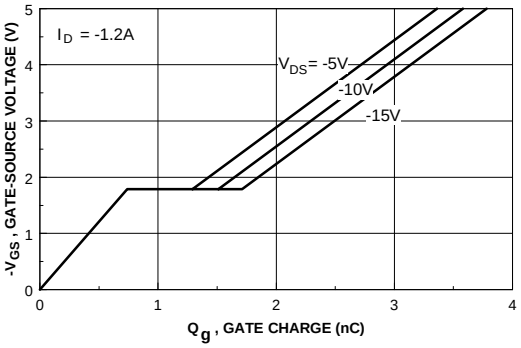


Figure 7. Gate-Charge Characteristics.

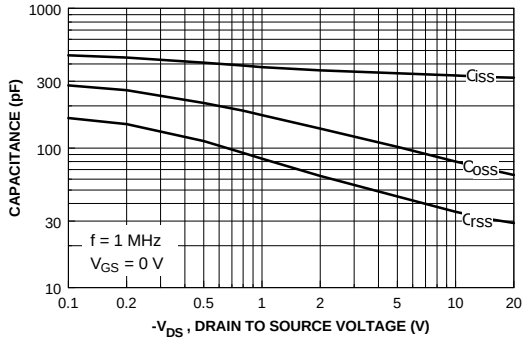


Figure 8. Capacitance Characteristics.

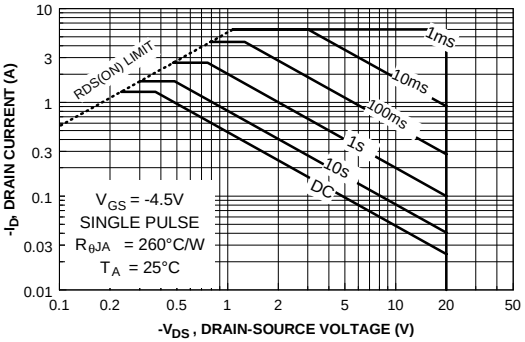


Figure 9. Maximum Safe Operating Area.

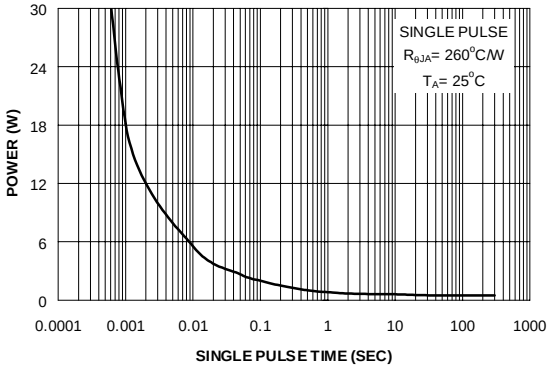


Figure 10. Single Pulse Maximum Power Dissipation.

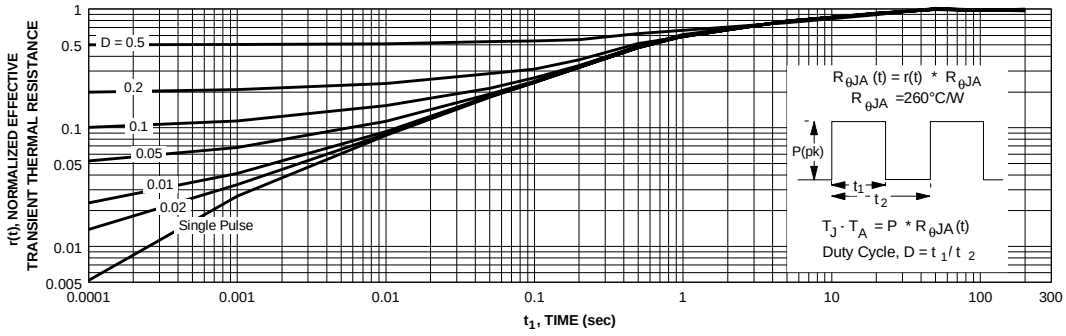


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.
Transient themal response will change depending on the circuit board design.

SC70-6 Tape and Reel Data and Package Dimensions

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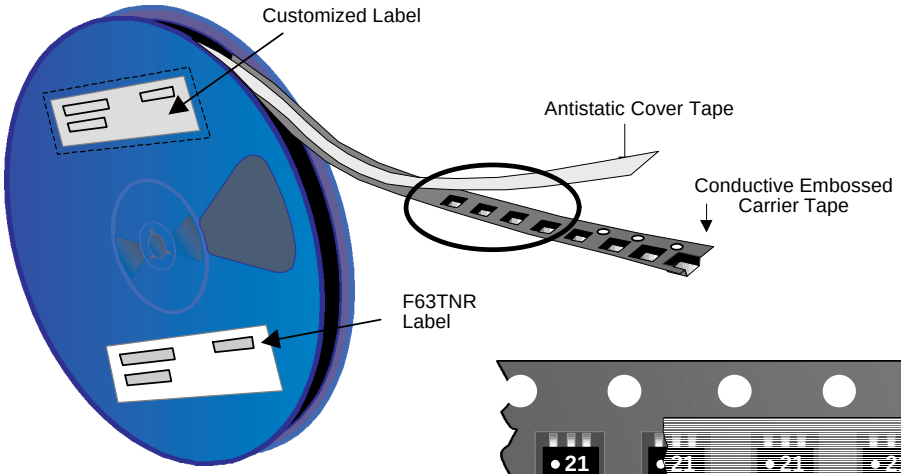
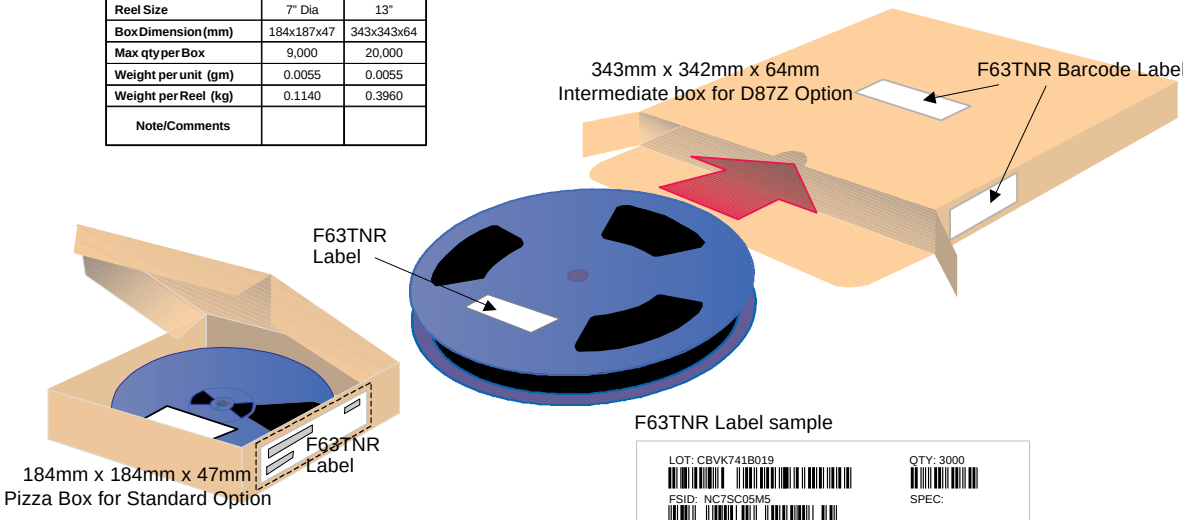
SC70-6 Packaging
Configuration: Figure 1.0



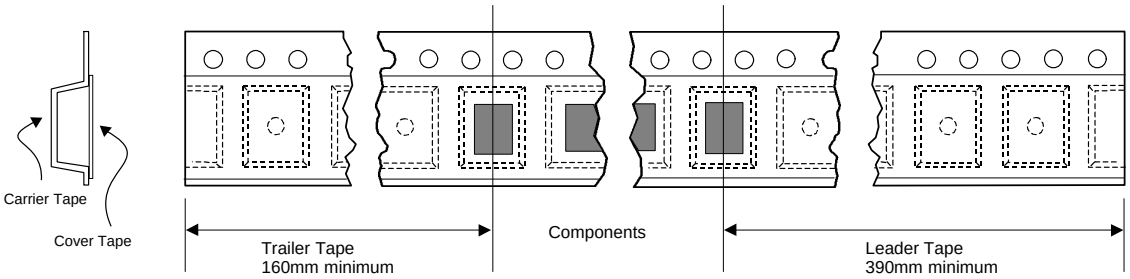
SC70-6 Unit Orientation

SC70-6 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	184x187x47	343x343x64
Max qty per Box	9,000	20,000
Weight per unit (gm)	0.0055	0.0055
Weight per Reel (kg)	0.1140	0.3960
Note/Comments		



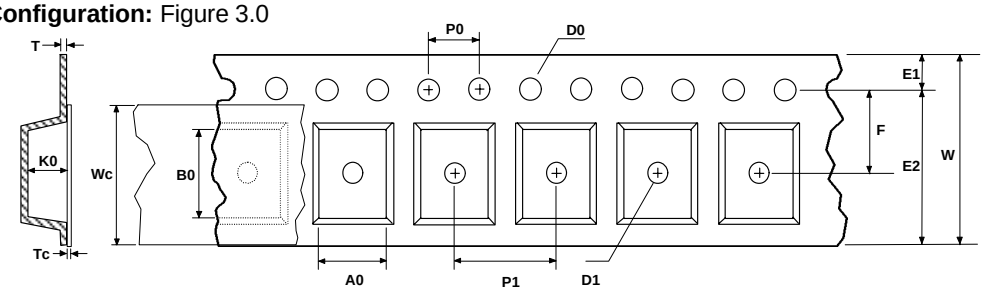
F63TNR Label sample

SC70-6 Tape Leader and Trailer
Configuration: Figure 2.0



SC70-6 Tape and Reel Data and Package Dimensions, continued

SC70-6 Embossed Carrier Tape
Configuration: Figure 3.0

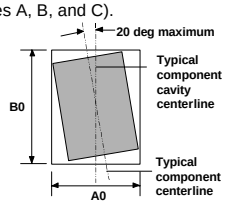


User Direction of Feed

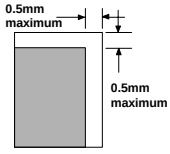
Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SC70-6 (8mm)	3.24 +/-0.10	2.34 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.00 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.20 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

Sketch A (Side or Front Sectional View)
Component Rotation

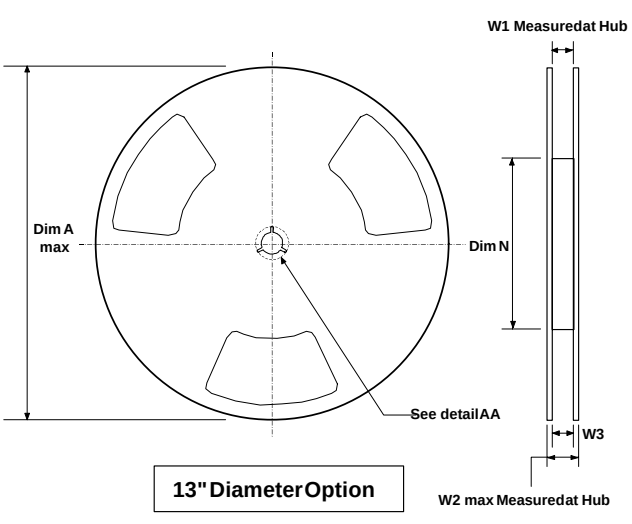


Sketch B (Top View)
Component Rotation

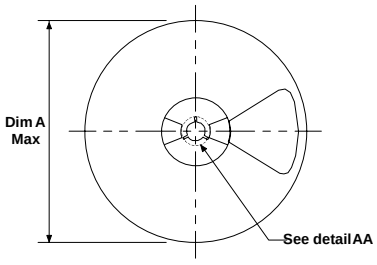


Sketch C (Top View)
Component lateral movement

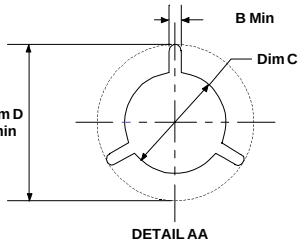
SC70-6 Reel Configuration: Figure 4.0



13" Diameter Option



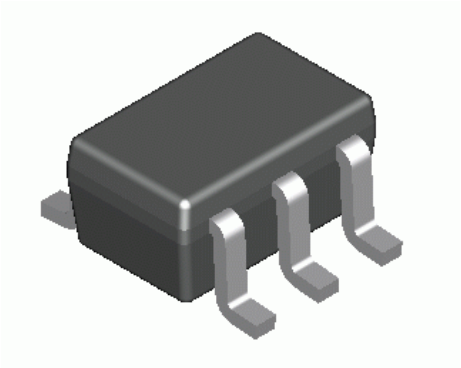
7" Diameter Option

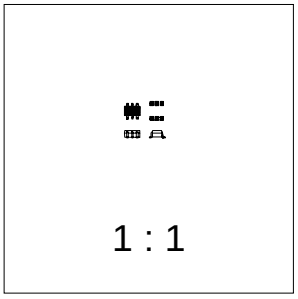


Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9

SC70-6 Tape and Reel Data and Package Dimensions, continued

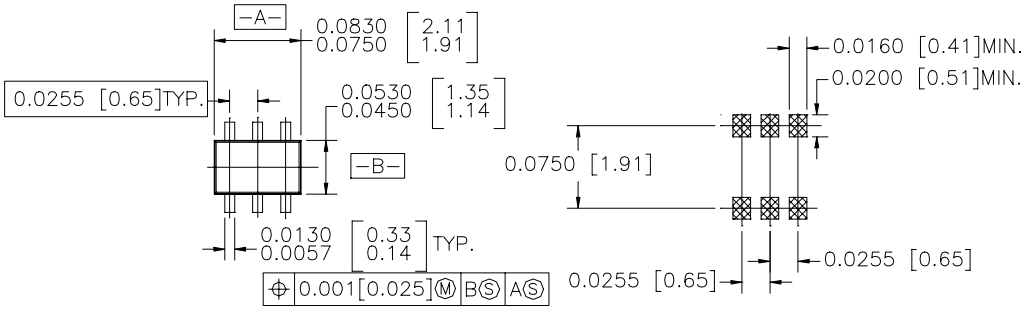
SC70-6 (FS PKG Code 76)



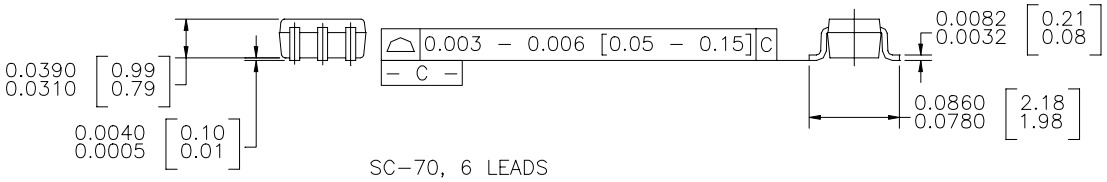


Scale 1:1 on letter size paper

Part Weight per unit (gram): 0.0055



LAND PATTERN RECOMMENDATION



SC–70, 6 LEADS

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